

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
STMICROELECTRONICS ASIA PACIFIC PTE LTD.	10/04/2011
RECEIVING PARTY DATA	
Name:	STMicroelectronics PTE LTD.
Street Address:	28 Ang Mo Kio Industrial Park 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	569508
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12330044
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	851663.480
NAME OF SUBMITTER:	Hayley J. Stevens
Total Attachments: 2 source=480 Assignment ST Asia Pac to ST PTE LTD#page1.tif source=480 Assignment ST Asia Pac to ST PTE LTD#page2.tif	

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ASSIGNMENT

WHEREAS, Assignor STMICROELECTRONICS ASIA PACIFIC PTE LTD., (hereinafter "Assignor") a Singapore corporation, was assigned certain rights in and to certain inventions, and application for Letters Patent of the United States entitled "MANUFACTURING FAN-OUT WAFER LEVEL PACKAGING," filed on December 8, 2008 as U.S. Application No. 12/330,044;

WHEREAS, STMICROELECTRONICS PTE LTD., a Singapore corporation, residing or having a principal place of business at 28 Ang Mo Kio Industrial Park 2, Singapore 569508 (hereinafter "Assignee"), is desirous of acquiring the entire right, title and interest in and to the inventions and the application for Letters Patent of the United States, and in and to any Letters Patent to be obtained therefor and thereon worldwide;

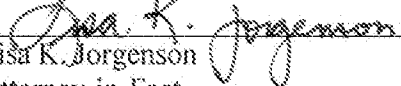
NOW, THEREFORE, for good and sufficient consideration, the receipt of which is acknowledged, to the extent Assignor had, or has any right, title, or interest in and to the inventions and application for Letters Patent, Assignor has sold, assigned, transferred and set over, and does sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, all right, title and interest in and to the above-mentioned inventions and application for Letters Patent that Assignor owns, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of the application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefor and thereon, and reissues, reexaminations and extensions of said Letters Patent, and any rights under the International Convention for the Protection of Industrial Property, same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignor, had this sale and assignment not been made;

AND Assignor requests the Commissioner of Patents and Trademarks to issue Letters Patent of the United States to Assignee, as Assignee of the inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns;

AND Assignor hereby grants the following individuals the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document: All practitioners at Customer Number 30423.

STMicroelectronics Asia Pacific Pte Ltd.

Date: October 4, 2011

Signature: 
Lisa K. Jorgenson
Attorney-in-Fact

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